Engineering Adhesives for Consumer Electronics
Bostik Born2Bond™ Engineering Adhesives enable manufacturers of consumer electronics to design and produce reliable, high-performance products that are easy to repair, maintain and recycle.

- Automation, in-line integration & high throughput
- Serviceability & repairability
- High precision, aesthetics & multi-substrates
- Sustainability & safety

**Smartwatch Assembly**

1. **Casing and Parts Assembly**
   - **Solutions:** Born2Bond™ High Performance HMPUR Adhesives
   - **Benefits:** Reliable bonding with HMPUR

2. **Electronics Encapsulation**
   - **Solutions:** Born2Bond™ UV Epoxy Adhesives, UV-Instant Adhesives, UV-Acrylic Adhesives
   - **Benefits:** Durable encapsulation and protection; fast curing

3. **Sealing and Gasketing**
   - **Solutions:** Born2Bond™ UV-CIPG Gasketing, UV-Acrylic Adhesives
   - **Benefits:** Serviceable gasketing with UV-CIPG; highly durable

4. **Battery Cell Assembly**
   - **Solutions:** Born2Bond™ UV Instant Adhesives, Instant Adhesives, Thermelt® Low Pressure Bio-Based Molding Hotmelt
   - **Benefits:** High-precision assembly; molding options for media resistance

5. **PCB Assembly**
   - **Solutions:** Born2Bond™ UV Instant Adhesives, Thermelt® Low Pressure Bio-Based Molding Hotmelt
   - **Benefits:** Durability; encapsulation and protection; fast curing; molding options

Explore Bostik’s full range of electronics assembly and bonding solutions Born2Bond Bostik.com/electronics

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VR HEADSET ASSEMBLY

1. MICROPHONE AND SPEAKER MANUFACTURING AND ASSEMBLY
   **SOLUTIONS:** Born2Bond™ High Performance HMPUR Adhesives
   **BENEFITS:** Reliable bonding with HMPUR

2. THREADLOCKING OF SCREWS
   **SOLUTIONS:** Born2Bond™ Anaerobic Adhesives
   **BENEFITS:** Vibration, corrosion & chemical resistance; non-CLP WL range

3. OPTICAL SENSOR ENCAPSULATION AND BONDING
   **SOLUTIONS:** Born2Bond™ UV Instant Adhesives, UV-Epoxy Adhesives, UV-Acrylic Adhesives
   **BENEFITS:** Durability; encapsulation and protection; fast curing

4. FRONT COVER TO FRAME BONDING
   **SOLUTIONS:** Born2Bond™-UV-CIPG Gasketing, High Performance HMPUR Adhesives
   **BENEFITS:** Reliable bonding with HMPUR; serviceable gasketing with UV-CIPG

5. ELECTRONICS ENCAPSULATION AND PCB ASSEMBLY
   **SOLUTIONS:** Born2Bond™ UV-Epoxy Adhesives, UV Instant Adhesives, UV-Acrylic Adhesives, Thermelt® Low Pressure Bio-Based Molding Hotmelt
   **BENEFITS:** Durable encapsulation and protection; fast curing; molding options

6. BATTERY AND ACOUSTIC ASSEMBLY
   **SOLUTIONS:** Born2Bond™ UV-Epoxy Adhesives, UV-Acrylic Adhesives, Thermelt® Low Pressure Bio-Based Molding Hotmelt
   **BENEFITS:** High strength and precision assembly; molding options for media resistance

7. CONNECTOR AND CABLE OVERMOLDING
   **SOLUTIONS:** Thermelt® Low Pressure Bio-Based Molding Hotmelt
   **BENEFITS:** Molding options for media resistance

8. LENS AND DISPLAY BONDING
   **SOLUTIONS:** Born2Bond™ UV-Epoxy Adhesives, UV-Acrylic Adhesives
   **BENEFITS:** High strength and precision assembly

9. DECORATION AND LOGO BONDING
   **SOLUTIONS:** Born2Bond™ UV Instant Adhesives
   **BENEFITS:** Fast curing

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Components for illustrative purposes only.
LAPTOP ASSEMBLY

1. ENCLOSURE ASSEMBLY
   SOLUTIONS: Born2Bond™ UV-CIPG Gasketing (serviceable), High Performance HMPUR Adhesives (non-serviceable), Instant Adhesives, 2K MMA
   BENEFITS: Reliable bonding with HMPUR; serviceable gasketing with UV-CIPG; multi-substrates

2. BATTERY CELL ASSEMBLY
   SOLUTIONS: Born2Bond™ UV Instant Adhesives, Instant Adhesives, Thermelt™ Low Pressure Bio-Based Molding Hotmelt
   BENEFITS: High-precision assembly; molding options for media resistance

3. ELECTRONICS ENCAPSULATION
   SOLUTIONS: Born2Bond™ UV Epoxy Adhesives, UV-Instant Adhesives, UV-Acrylic Adhesives
   BENEFITS: Durable encapsulation and protection; fast curing

4. THREADLOCKING OF SCREWS
   SOLUTIONS: Born2Bond™ Anaerobic Adhesives
   BENEFITS: Vibration, corrosion & chemical resistance; non-CLP WL range

5. PCB ASSEMBLY
   SOLUTIONS: Born2Bond™ UV Instant Adhesives, Thermelt™ Low Pressure Bio-Based Molding Hotmelt
   BENEFITS: Durability; encapsulation and protection; fast curing, molding options

6. DISPLAY PANEL BONDING
   SOLUTIONS: Born2Bond™ UV-CIPG Gasketing (serviceable), High Performance HMPUR Adhesives (non-serviceable)
   BENEFITS: Reliable bonding with HMPUR; serviceable gasketing with UV-CIPG; multi-substrates

7. TOUCHPAD ASSEMBLY
   SOLUTIONS: Born2Bond™ UV Epoxy Adhesives, UV Instant Adhesives, UV-Acrylic Adhesives
   BENEFITS: High strength and protection; fast curing

8. SPEAKER ASSEMBLY
   SOLUTIONS: Born2Bond™ High Performance HMPUR Adhesives, Instant Adhesives, UV-Acrylic Adhesives
   BENEFITS: Reliable bonding with HMPUR; fast curing

Components for illustrative purposes only.
**SMARTPHONE ASSEMBLY**

1. **THREADLOCKING OF SCREWS**
   - **SOLUTIONS:** Born2Bond™ Anaerobic Adhesives
   - **BENEFITS:** Vibration, corrosion & chemical resistance; non-CLP WL range

2. **PCB ASSEMBLY**
   - **SOLUTIONS:** Born2Bond™ UV Instant Adhesives, Thermelt® Low Pressure Bio-Based Molding Hotmelt
   - **BENEFITS:** Durability; encapsulation and protection; fast curing; molding options

**ENGINEERING ADHESIVES FOR CONSUMER ELECTRONICS**

3. **ENCLOSURE ASSEMBLY**
   - **SOLUTIONS:** Born2Bond™ High Performance HMPUR Adhesives (non-serviceable), Instant Adhesives
   - **BENEFITS:** Reliable bonding with HMPUR; multi-substrates

4. **CAMERA MODULE ASSEMBLY**
   - **SOLUTIONS:** Born2Bond™ High Performance HMPUR Adhesives (non-serviceable), Instant Adhesives, Thermelt® Low Pressure Bio-Based Molding Hotmelt
   - **BENEFITS:** High-precision assembly; molding options for media resistance

5. **DISPLAY/TOUCH PANEL BONDING**
   - **SOLUTIONS:** Born2Bond™ High Performance HMPUR Adhesives (non-serviceable)
   - **BENEFITS:** Reliable bonding with HMPUR; multi-substrates

6. **BATTERY CELL ASSEMBLY**
   - **SOLUTIONS:** Born2Bond™ UV Instant Adhesives, Instant Adhesives, Thermelt® Low Pressure Bio-Based Molding Hotmelt
   - **BENEFITS:** High-precision assembly; molding options for media resistance

7. **ELECTRONICS ENCAPSULATION**
   - **SOLUTIONS:** Born2Bond™ UV Epoxy Adhesives, UV-Instant Adhesives, UV-Acrylic Adhesives
   - **BENEFITS:** Durable encapsulation and protection; fast curing

8. **ACOUSTIC ASSEMBLY**
   - **SOLUTIONS:** Born2Bond™ High Performance HMPUR Adhesives, UV-Acrylic Adhesives
   - **BENEFITS:** Reliable bonding with HMPUR
All Born2Bond™ Engineering Adhesives are suitable for small production runs using manual application, as well as semi- or fully-automated production lines.

### BORN2BOND™ INSTANT and UV-INSTANT ADHESIVES
- Low odor and low bloom solutions available for increased user comfort and uncompromised fine finishes
- Dual-cure adhesives feature ‘cure-on-demand’ properties for increased throughput and cure of excess material (patented Light Lock grades only)
- Fast bonding solutions available for enhanced reliability and durability
- Automatic, semi-automatic and manual high-precision dispensing options

### BORN2BOND™ UV-EPOXY and UV-ACRYLIC ADHESIVES
- Highly durable - impact, chemical and temperature resistant
- Multi-substrate adhesion to metals, glass and plastics (including ABS and PMMA)
- Suitable for high precision and high-speed automated dispensing using a wide variety of equipment and methods
- Wide UV wavelength range
- Available in multiple viscosities

### BORN2BOND™ HIGH PERFORMANCE HMPUR ADHESIVES
- Multi-substrate adhesion
- High temperature, humidity and chemical resistance
- Good balance between strength and elasticity
- Designed for manual, semi-automatic and automated dispensing for high-precision applications
- Extensive range, with tailor-made solutions available

### BORN2BOND™ UV-CIPG GASKETING
- Serviceability of assembled and sealed parts and enclosures
- Waterproofing and dustproofing for increased durability
- Resistant to chemicals and temperature fluctuations
- Extremely flexible and durable
- Designed for semi-automatic and automated dispensing for high-precision applications

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**HIGH PERFORMANCE POLYMERS**

Beyond Bostik’s portfolio as the adhesive solutions division, Arkema also offers pioneering high-performance polymers from renewable sources to customers from a broad range of markets. Bio-based and recyclable Rilsan® Polyamide 11 is chosen by manufacturers for its lightweight properties, flexibility or high rigidity when required, good UV resistance, overall durability as well as easy processibility. Piezotech® electroactive polymers for organic, printed and flexible electronics make it possible to design the next generation of sensors, speakers, haptic devices and more – making them ideal for consumer electronics applications.

For more information and to order free Born2Bond™ samples, please visit: [Born2Bond.Bostik.com](http://Born2Bond.Bostik.com)

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